MW-G / MLS™-G / MLS™-G2 / MLS™-G3

高密度互連板(HDI)細線路用低粗度銅箔
Low profile copper foil for the Ultra fine line HDI

- 三井薄銅低粗度特性應用於高密度互連板之極細線路設計, 具優越的蝕刻性 / 優良的抗斯強度 / 極佳的耐熱特性.
- Mitsui Kinzoku thin and low roughness copper foils; Suitable for fine line HDI design with excellent etchability, bonding strength, and heat resistance properties.
- 穩定量產能力, 可充分供應客戶的需求.
- Good track records of reliable and advanced production capability to fulfill customers' volume requirements.

Product	Cross Section Image	Roughness (Bonding side-Rz)	Thickness	Application (L/S)	Status
MW-G		4.0μm	12 μm	≧ 50/50μm	Mass Production
MLS™-G		3.0μm	12 μm	40/40 ~ 50/50μm	
MLS™-G2		2.0μm	12 μm	30/30 ~ 40/40μm	
MLS™-G3		1.5μm	12μm	30/30 ~ 40/40μm for 5G	

* 上述表列為代表性資料,非保證值. * This is representative data not guarantee